



## PALLV22V10 and PALLV22V10Z Families

### Low-Voltage (Zero Power) 24-Pin EE CMOS Versatile PAL Device

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#### DISTINCTIVE CHARACTERISTICS

- ◆ Low-voltage operation, 3.3 V JEDEC compatible
  - $V_{CC} = +3.0\text{ V to }3.6\text{ V}$
- ◆ Commercial and industrial operating temperature range
- ◆ 7.5-ns  $t_{PD}$
- ◆ Electrically-erasable technology provides reconfigurable logic and full testability
- ◆ 10 macrocells programmable as registered or combinatorial, and active high or active low to match application needs
- ◆ Varied product term distribution allows up to 16 product terms per output for complex functions
- ◆ Global asynchronous reset and synchronous preset for initialization
- ◆ Power-up reset for initialization and register preload for testability
- ◆ Extensive third-party software and programmer support
- ◆ 24-pin SKINNY DIP and 28-pin PLCC packages save space

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#### GENERAL DESCRIPTION

The PALLV22V10 is an advanced PAL<sup>®</sup> device built with low-voltage, high-speed, electrically-erasable CMOS technology.

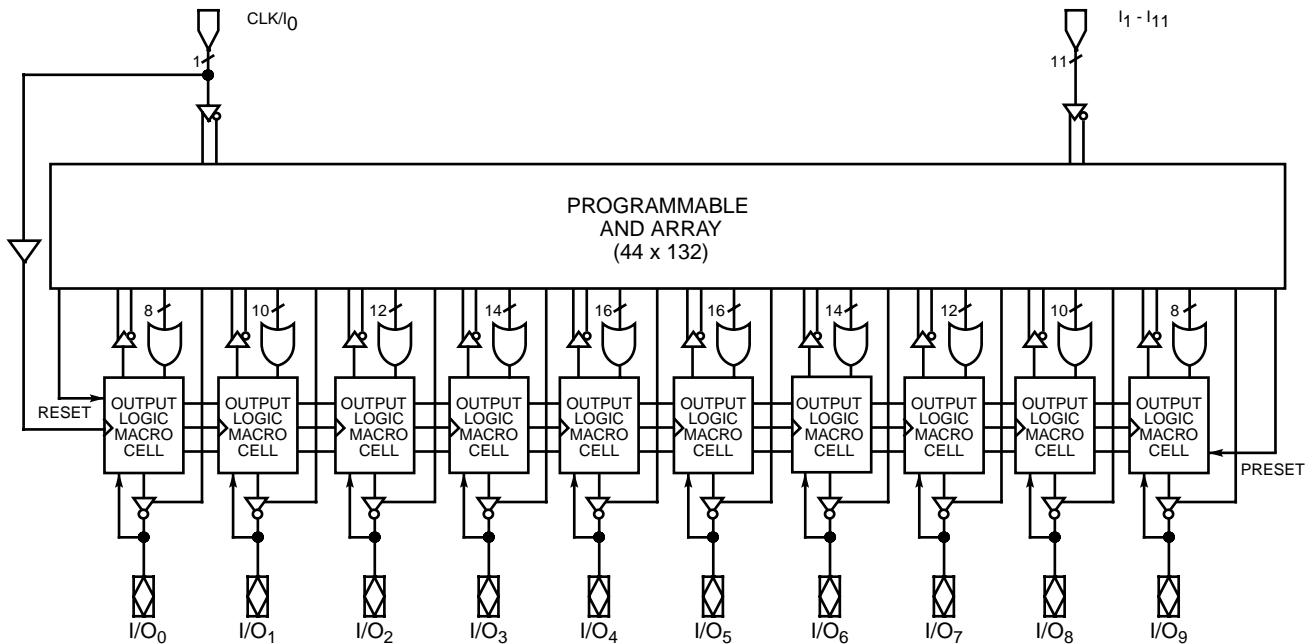
The PALLV22V10Z provides low voltage and zero standby power. At 30  $\mu\text{A}$  maximum standby current, the PALLV22V10Z allows battery powered operation for an extended period.

The PALLV22V10 device implements the familiar Boolean logic transfer function, the sum of products. The PAL device is a programmable AND array driving a fixed OR array. The AND array is programmed to create custom product terms, while the OR array sums selected terms at the outputs.

The product terms are connected to the fixed OR array with a varied distribution from 8 to 16 across the outputs (see Block Diagram). The OR sum of the products feeds the output macrocell. Each macrocell can be programmed as registered or combinatorial, and active high or active low. The output configuration is determined by two bits controlling two multiplexers in each macrocell.



## BLOCK DIAGRAM



18956D-001

## FUNCTIONAL DESCRIPTION

The PALLV22V10 is the low-voltage version of the PALCE22V10. It has all the architectural features of the PALCE22V10.

The PALLV2210Z is the low-voltage, zero-power version of the PALCE22V10. It has all the architectural features of the PALCE22V10. In addition, the PALLV22V10Z has zero standby power and an unused product term disable feature.

The PALLV22V10 allows the systems engineer to implement a design on-chip by programming EE cells to configure AND and OR gates within the device, according to the desired logic function. Complex interconnections between gates, which previously required time-consuming layout, are lifted from the PC board and placed on silicon, where they can be easily modified during prototyping or production.

Product terms with all connections opened assume the logical HIGH state; product terms connected to both true and complement of any single input assume the logical LOW state.

The PALLV22V10 has 12 inputs and 10 I/O macrocells. The macrocell (Figure 1) allows one of four potential output configurations; registered output or combinatorial I/O, active high or active low (see Figure 2). The configuration choice is made according to the user's design specification and corresponding programming of the configuration bits  $S_0 - S_1$ . Multiplexer controls are connected to ground (0) through a programmable bit, selecting the "0" path through the multiplexer. Erasing the bit disconnects the control line from GND and it floats to  $V_{CC}$  (1), selecting the "1" path.

The device is produced with a EE cell link at each input to the AND gate array, and connections may be selectively removed by applying appropriate voltages to the circuit. Utilizing an easily-implemented programming algorithm, these products can be rapidly programmed to any customized pattern.

## Variable Input/Output Pin Ratio

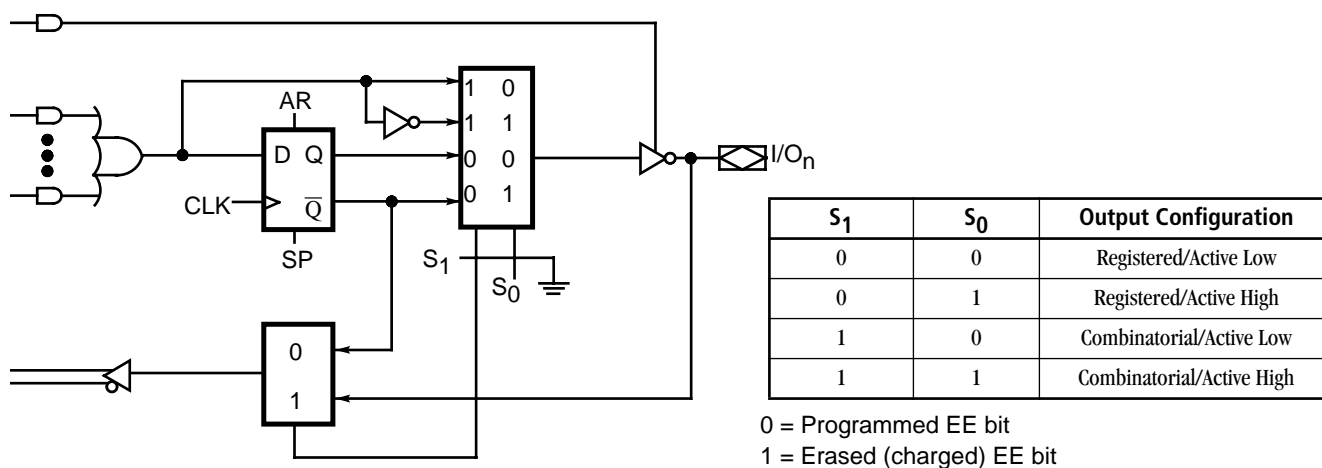
The PALLV22V10 has twelve dedicated input lines, and each macrocell output can be an I/O pin. Buffers for device inputs have complementary outputs to provide user-programmable input signal polarity. Unused input pins should be tied to  $V_{CC}$  or GND.

## Registered Output Configuration

Each macrocell of the PALLV22V10 includes a D-type flip-flop for data storage and synchronization. The flip-flop is loaded on the LOW-to-HIGH transition of the clock input. In the registered configuration ( $S_1 = 0$ ), the array feedback is from  $\bar{Q}$  of the flip-flop.

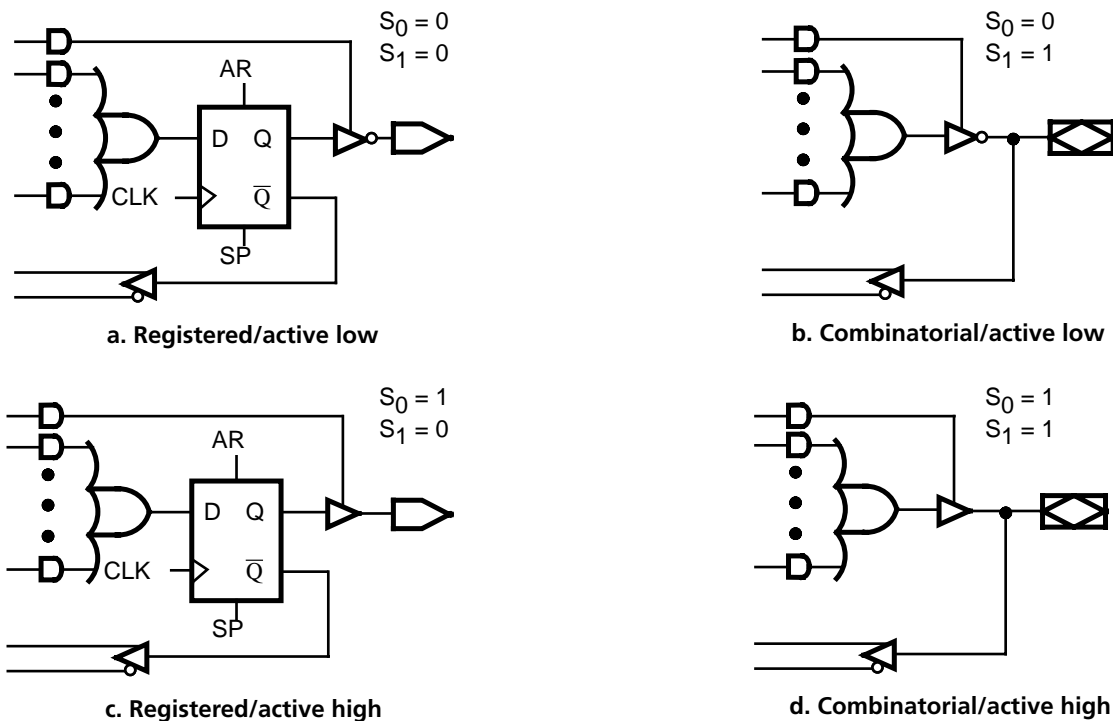
## Combinatorial I/O Configuration

Any macrocell can be configured as combinatorial by selecting the multiplexer path that bypasses the flip-flop ( $S_1 = 1$ ). In the combinatorial configuration, the feedback is from the pin.



18956C-004

Figure 1. Output Logic Macrocell Diagram



18956D-005

Figure 2. Macrocell Configuration Options

### Programmable Three-State Outputs

Each output has a three-state output buffer with three-state control. A product term controls the buffer, allowing enable and disable to be a function of any product of device inputs or output feedback. The combinatorial output provides a bi-directional I/O pin, and may be configured as a dedicated input if the buffer is always disabled.

### Programmable Output Polarity

The polarity of each macrocell output can be active high or active low, either to match output signal needs or to reduce product terms. Programmable polarity allows Boolean expressions to be written in their most compact form (true or inverted), and the output can still be of the desired polarity. It can also save “DeMorganizing” efforts.

Selection is controlled by programmable bit  $S_0$  in the output macrocell, and affects both registered and combinatorial outputs. Selection is automatic, based on the design specification and pin definitions. If the pin definition and output equation have the same polarity, the output is programmed to be active high ( $S_0 = 1$ ).

### Preset/Reset

For initialization, the PALLV22V10 has additional preset and reset product terms. These terms are connected to all registered outputs. When the synchronous preset (SP) product term is asserted high, the output registers will be loaded with a HIGH on the next LOW-to-HIGH clock transition. When the asynchronous reset (AR) product term is asserted high, the output registers will be immediately loaded with a LOW independent of the clock.



Note that preset and reset control the flip-flop, not the output pin. The output level is determined by the output polarity selected.

### **Benefits of Lower Operating Voltage**

The PALLV22V10 has an operating voltage range of 3.0 V to 3.6 V. Low voltage allows for lower operating power consumption, longer battery life, and/or smaller batteries for notebook applications.

Because power is proportional to the square of the voltage, reduction of the supply voltage from 5.0 V to 3.3 V significantly reduces power consumption. This directly translates to longer battery life for portable applications. Lower power consumption can also be used to reduce the size and weight of the battery. Thus, 3.3 V designs facilitate a reduction in the form factor.

A lower operating voltage results in a reduction of I/O voltage swings. This reduces noise generation and provides a less hostile environment for board design. A lower operating voltage also reduces electromagnetic radiation noise and makes obtaining FCC approval easier.

### **3.3-V (CMOS) and 5-V (CMOS and TTL) Compatible Inputs and I/O**

Input voltages can be at TTL levels. Additionally, the PALLV22V10 can be driven with true 5-V CMOS levels due to special input and I/O buffer circuitry.

### **Power-Up Reset**

All flip-flops power up to a logic LOW for predictable system initialization. Outputs of the PALLV22V10 will depend on the programmed output polarity. The  $V_{CC}$  rise must be monotonic, and the reset delay time is 1000ns maximum.

### **Register Preload**

The registers on the PALLV22V10 can be preloaded from the output pins to facilitate functional testing of complex state machine designs. This feature allows direct loading of arbitrary states, making it unnecessary to cycle through long test vector sequences to reach a desired state. In addition, transitions from illegal states can be verified by loading illegal states and observing proper recovery.

### **Security Bit**

After programming and verification, a PALLV22V10 design can be secured by programming the security EE bit. Once programmed, this bit defeats readback of the internal programmed pattern by a device programmer, securing proprietary designs from competitors. When the security bit is programmed, the array will read as if every bit is erased, and preload will be disabled.

The bit can only be erased in conjunction with erasure of the entire pattern.

### **Programming and Erasing**

The PALLV22V10 can be programmed on standard logic programmers. It also may be erased to reset a previously configured device back to its unprogrammed state. Erasure is automatically performed by the programming hardware. No special erase operation is required.



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## Quality and Testability

The PALLV22V10 offers a very high level of built-in quality. The erasability of the CMOS PALLV22V10 allows direct testing of the device array to guarantee 100% programming and functional yields.

## Technology

The high-speed PALLV22V10 is fabricated with Vantis' advanced electrically-erasable (EE) CMOS process. The array connections are formed with proven EE cells. Inputs and outputs are designed to be 3.3-V and 5-V device compatible. This technology provides strong input-clamp diodes, output slew-rate control, and a grounded substrate for clean switching.

## Zero-Standby Power Mode

The PALLV22V10Z features a zero-standby power mode. When none of the inputs switch for an extended period (typically 30 ns), the PALLV22V10Z will go into standby mode, shutting down most of its internal circuitry. The current will go to almost zero ( $I_{CC} < 30 \mu\text{A}$ ). The outputs will maintain the states held before the device went into the standby mode.

If a macrocell is used in registered mode, switching pin CLK/I<sub>0</sub> will not affect standby mode status for that macrocell. If a macrocell is used in combinatorial mode, switching pin CLK/I<sub>0</sub> will affect standby mode status for that macrocell.

This feature reduces dynamic  $I_{CC}$  proportionally to the number of registered macrocells used. If all macrocells are used as registers and only CLK/I<sub>0</sub> is switching, the device will not be in standby mode, but dynamic  $I_{CC}$  will typically be  $< 2 \text{ mA}$ . This is because only the CLK/I<sub>0</sub> buffer will draw current. The use of combinatorial macrocells will add on average 5 mA per macrocell (at 25 MHz) under these same conditions.

When any input switches, the internal circuitry is fully enabled, and power consumption returns to normal. This feature results in considerable power savings for operation at low to medium frequencies.

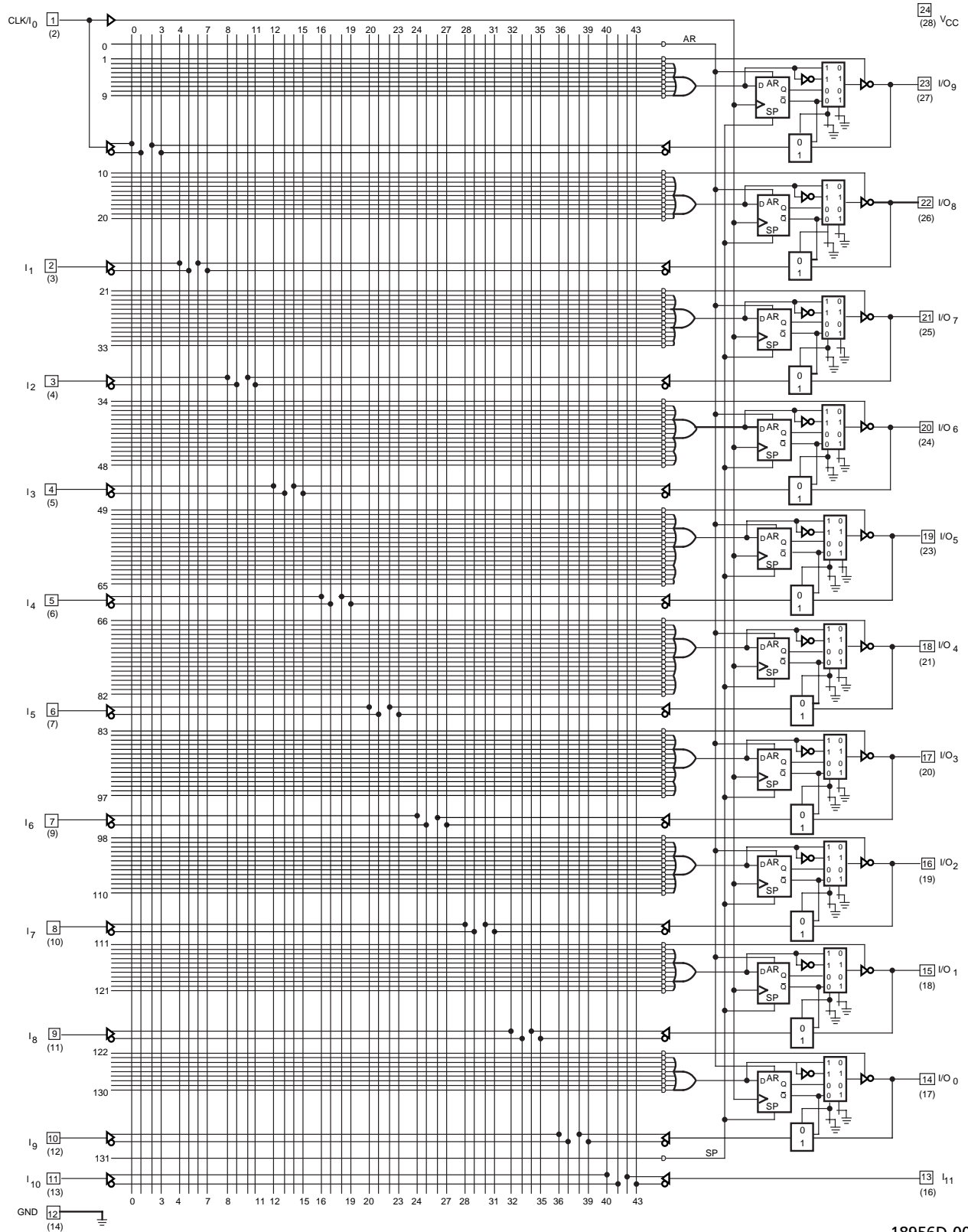
## Product-Term Disable

On a programmed PALLV22V10Z, any product terms that are not used are disabled. Power is cut off from these product terms so that they do not draw current. Product-term disabling results in considerable power savings. This saving is greater at the higher frequencies.

Further hints on minimizing power consumption can be found in a separate document entitled, *Minimizing Power Consumption with Zero-Power PLDs*.



# LOGIC DIAGRAM



PAL Devices

18956D-006



## ABSOLUTE MAXIMUM RATINGS

Storage Temperature . . . . .	-65°C to +150°C
Ambient Temperature with Power Applied . . . . .	-55°C to +125°C
Supply Voltage with Respect to Ground . . . . .	-0.5 V to +7.0 V
DC Input Voltage . . . . .	-0.5 V to +5.25 V
DC Output or I/O Pin Voltage . . . . .	-0.5 V to +5.25 V
Static Discharge Voltage . . . . .	2001 V
Latchup Current ( $T_A = 0^\circ\text{C}$ to $+75^\circ\text{C}$ ) . . . . .	100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

## OPERATING RANGES

### Commercial (C) Devices

Ambient Temperature ( $T_A$ ) . . . . .	$0^\circ\text{C}$ to $+75^\circ\text{C}$
Supply Voltage ( $V_{CC}$ ) with Respect to Ground. . . . .	+3.0 V to +3.6 V

### Industrial (I) Devices

Ambient Temperature ( $T_A$ ) . . . . .	$-40^\circ\text{C}$ to $+85^\circ\text{C}$
Supply Voltage ( $V_{CC}$ ) with Respect to Ground. . . . .	+3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

## DC CHARACTERISTICS OVER COMMERCIAL AND INDUSTRIAL OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit	
$V_{OH}$	Output HIGH Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{CC} = \text{Min}$	$I_{OH} = -2 \text{ mA}$	2.4		V
			$I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.2$		V
$V_{OL}$	Output LOW Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 16 \text{ mA}$		0.5	V
			$I_{OL} = 100 \mu\text{A}$		0.2	V
$V_{IH}$	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Notes 1, 2)	2.0	5.25	V	
$V_{IL}$	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Notes 1, 2)		0.8	V	
$I_{IH}$	Input HIGH Leakage Current	$V_{IN} = V_{CC}$ , $V_{CC} = \text{Max}$ (Note 2)		10	$\mu\text{A}$	
$I_{IL}$	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 2)		-100	mA	
$I_{OZH}$	Off-State Output Leakage Current HIGH	$V_{OUT} = V_{CC}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)		10	mA	
$I_{OZL}$	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)		-100	mA	
$I_{SC}$	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 3)	-5	-75	mA	
$I_{CC}$ (Static)	Supply Current	Outputs $f = 0 \text{ MHz}$ , Open ( $I_{OUT} = 0 \text{ mA}$ )	-10/15 Commercial		60	mA
			-7		75	mA
			-15 Industrial		75	mA

### Notes:

- These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
- I/O pin leakage is the worst case of  $I_{IL}$  and  $I_{OZL}$  (or  $I_{IH}$  and  $I_{OZH}$ ).
- Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.





## CAPACITANCE <sup>1</sup>

Parameter Symbol	Parameter Description	Test Condition		Typ	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 2.0 V	V <sub>CC</sub> = 3.3 V T <sub>A</sub> = 25°C f = 1 MHz	5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 2.0 V		8	

**Note:**

1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

## SWITCHING CHARACTERISTICS OVER COMMERCIAL AND INDUSTRIAL OPERATING RANGES <sup>1</sup>

Parameter Symbol	Parameter Description		-7		-10		-15		Unit	
			Min	Max	Min	Max	Min	Max		
t <sub>PD</sub>	Input or Feedback to Combinatorial Output			7.5		10		15	ns	
t <sub>S1</sub>	Setup Time from Input, Feedback or SP to Clock		4.5		5.5		10		ns	
t <sub>S2</sub>	Setup Time from SP to Clock		5.5		7		10		ns	
t <sub>H</sub>	Hold Time		0		0		0		ns	
t <sub>CO</sub>	Clock to Output			5.5		6.5		10	ns	
t <sub>AR</sub>	Asynchronous Reset to Registered Output			11		13		20	ns	
t <sub>ARW</sub>	Asynchronous Reset Width		6		8		10		ns	
t <sub>ARR</sub>	Asynchronous Reset Recovery Time		6		8		10		ns	
t <sub>SPR</sub>	Synchronous Preset Recovery Time		6		8		10		ns	
t <sub>WL</sub>	Clock Width	LOW	3.5		4		6		ns	
t <sub>WH</sub>		HIGH	3.5		4		6		ns	
f <sub>MAX</sub>	Maximum Frequency (Note 2)	External Feedback	1/(t <sub>S</sub> + t <sub>CO</sub> )		100		83.3		50	MHz
		Internal Feedback (t <sub>CNT</sub> )	1/(t <sub>S</sub> + t <sub>CF</sub> ) (Note 3)		133		110		58.8	MHz
		No Feedback	1/(t <sub>WH</sub> + t <sub>WL</sub> )		143		125		83.3	MHz
t <sub>EA</sub>	Input to Output Enable Using Product Term Control			9		11		15	ns	
t <sub>ER</sub>	Input to Output Disable Using Product Term Control			10		11		15	ns	

**Notes:**

1. See "Switching Test Circuit" for test conditions.
2. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where frequency may be affected.
3. t<sub>CF</sub> is a calculated value and is not guaranteed. t<sub>CF</sub> can be found using the following equation:  

$$t_{CF} = 1/f_{MAX} \text{ (internal feedback)} - t_S$$



## ABSOLUTE MAXIMUM RATINGS

Storage Temperature . . . . . -65°C to +150°C  
 Ambient Temperature with  
 Power Applied . . . . . -55°C to +125°C  
 Supply Voltage with  
 Respect to Ground . . . . . -0.5 V to +7.0 V  
 DC Input Voltage . . . . . -0.5 V to +5.5 V  
 DC Output or I/O Pin Voltage . . . . . -0.5 V to +5.5 V  
 Static Discharge Voltage . . . . . 2001 V  
 Latchup Current ( $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ). . . . . 100 mA

*Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.*

## OPERATING RANGES

### Industrial (I) Devices

Ambient Temperature ( $T_A$ ) . . . . . -40°C to +85°C  
 Supply Voltage ( $V_{CC}$ ) with  
 Respect to Ground. . . . . +3.0 V to +3.6 V  
*Operating ranges define those limits between which the functionality of the device is guaranteed.*

## DC CHARACTERISTICS OVER INDUSTRIAL OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
$V_{OH}$	Output HIGH Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{CC} = \text{Min}$	$I_{OH} = -2 \text{ mA}$	2.4	V
			$I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.3$	V
$V_{OL}$	Output LOW Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{CC} = \text{Min}$	$I_{OL} = 2 \text{ mA}$	0.4	V
			$I_{OL} = 100 \mu\text{A}$	0.2	V
$V_{IH}$	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0	5.5	V
$V_{IL}$	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	V
$I_{IH}$	Input HIGH Leakage Current	$V_{IN} = V_{CC}$ , $V_{CC} = \text{Max}$		10	$\mu\text{A}$
$I_{IL}$	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$ , $V_{CC} = \text{Max}$		-10	$\mu\text{A}$
$I_{OZH}$	Off-State Output Leakage Current HIGH	$V_{OUT} = V_{CC}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)		10	$\mu\text{A}$
$I_{OZL}$	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)		-10	$\mu\text{A}$
$I_{SC}$	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 3)	-5	-75	mA
$I_{CC}$	Supply Current	Outputs Open ( $I_{OUT} = 0 \text{ mA}$ ) $V_{CC} = \text{Max}$ (Note 4)	$f = 0 \text{ MHz}$	30	$\mu\text{A}$
			$f = 15 \text{ MHz}$	55	mA

### Notes:

1. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
2. I/O pin leakage is the worst case of  $I_{IL}$  and  $I_{OZL}$  (or  $I_{IH}$  and  $I_{OZH}$ ).
3. Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.
4. This parameter is guaranteed under worst case test conditions. Refer to the  $I_{CC}$  vs. Frequency graph in this datasheet for typical  $I_{CC}$  characteristics.



## CAPACITANCE <sup>1</sup>

Parameter Symbol	Parameter Description	Test Condition		Typ	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 2.0 V	V <sub>CC</sub> = 3.3 V	5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 2.0 V	T <sub>A</sub> = 25°C f = 1 MHz	8	

### Note:

1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

## SWITCHING CHARACTERISTICS OVER INDUSTRIAL OPERATING RANGES <sup>1</sup>

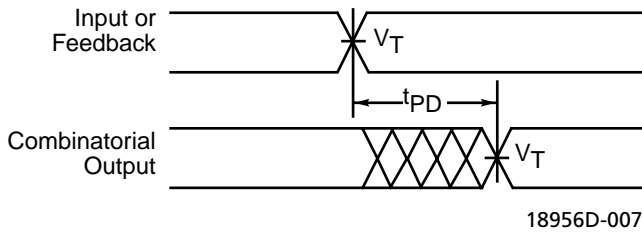
Parameter Symbol	Parameter Description	-25		Unit	
		Min	Max		
t <sub>PD</sub>	Input or Feedback to Combinatorial Output (Note 2)		25	ns	
t <sub>S</sub>	Setup Time from Input, Feedback or SP to Clock	15		ns	
t <sub>H</sub>	Hold Time	0		ns	
t <sub>CO</sub>	Clock to Output		15		
t <sub>AR</sub>	Asynchronous Reset to Registered Output		25	ns	
t <sub>ARW</sub>	Asynchronous Reset Width	25		ns	
t <sub>ARR</sub>	Asynchronous Reset Recovery Time	25		ns	
t <sub>SPR</sub>	Synchronous Preset Recovery Time	25		ns	
t <sub>WL</sub>	Clock Width	LOW	10	ns	
t <sub>WH</sub>		HIGH	10	ns	
f <sub>MAX</sub>	Maximum Frequency (Note 3)	External Feedback	1/(t <sub>S</sub> + t <sub>CO</sub> )	33.3	MHz
		Internal Feedback (f <sub>CNT</sub> )	1/(t <sub>S</sub> + t <sub>CF</sub> ) (Note 4)	35.7	MHz
		No Feedback	1/(t <sub>WH</sub> + t <sub>WL</sub> )	50	MHz
t <sub>EA</sub>	Input to Output Enable Using Product Term Control		25	ns	
t <sub>ER</sub>	Input to Output Disable Using Product Term Control		25	ns	

### Notes:

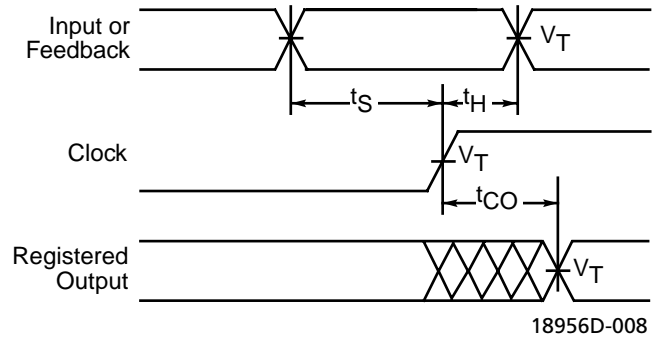
1. See "Switching Test Circuit" for test conditions.
2. This parameter is tested in Standby Mode. When the device is not in Standby Mode, the t<sub>PD</sub> may be slightly faster.
3. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where frequency may be affected.
4. t<sub>CF</sub> is a calculated value and is not guaranteed. t<sub>CF</sub> can be found using the following equation:  
t<sub>CF</sub> = 1/f<sub>MAX</sub> (internal feedback) - t<sub>S</sub>.



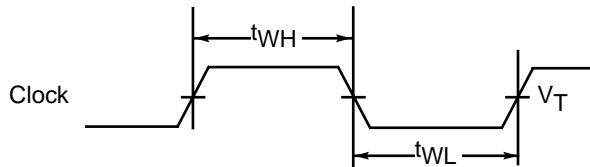
## SWITCHING WAVEFORMS



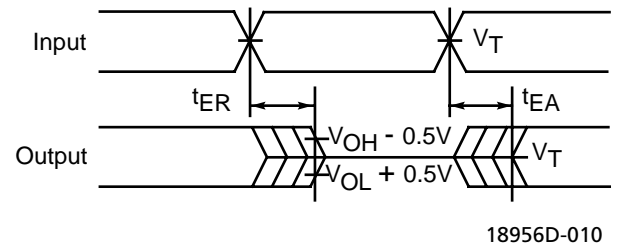
a. Combinatorial output



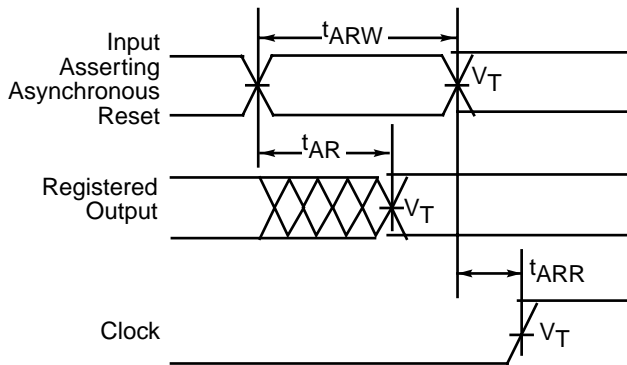
b. Registered output



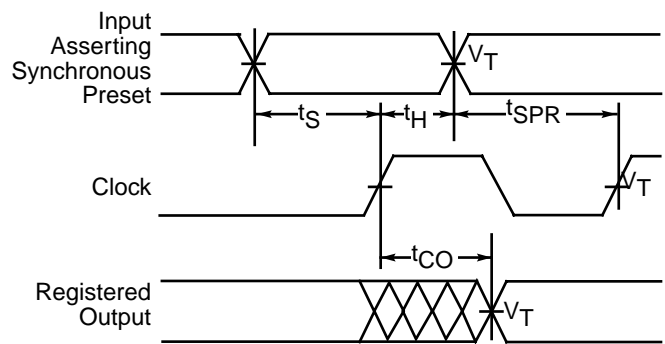
c. Clock width



d. Input to output disable/enable



e. Asynchronous reset



f. Synchronous preset

### Notes:

1.  $V_T = 1.5\text{ V}$  for inputs signals and  $V_{CC}/2$  for outputs signals.
2. Input pulse amplitude 0 V to 3.0 V.
3. Input rise and fall times 2 ns to 5 ns typical.

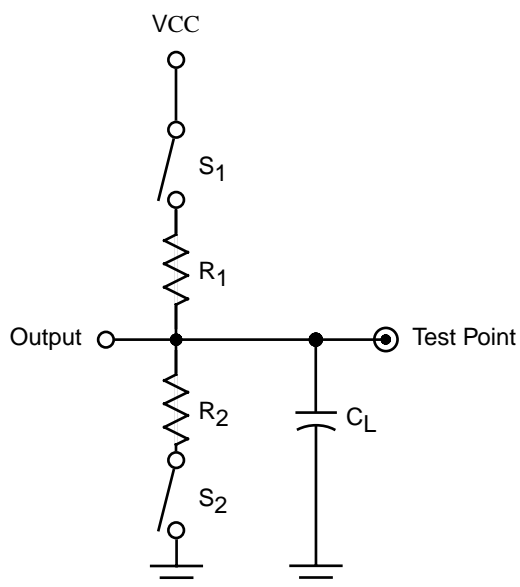


## KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	Must be Steady	Will be Steady
	May Change from H to L	Will be Changing from H to L
	May Change from L to H	Will be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
	Does Not Apply	Center Line is High-Impedance "Off" State

18956D-013

## SWITCHING TEST CIRCUIT



18956D-014

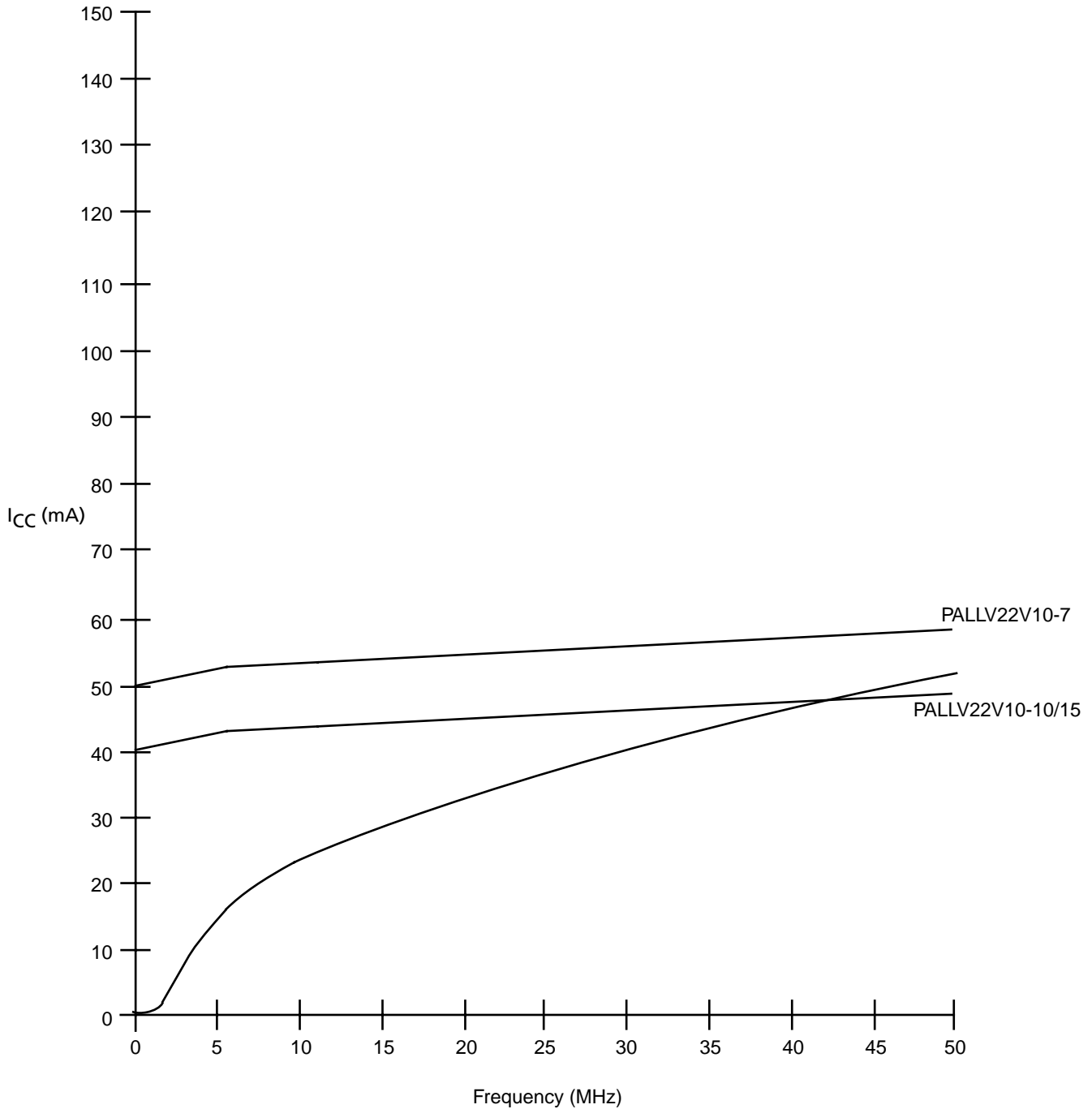
Specification	S <sub>1</sub>	S <sub>2</sub>	C <sub>L</sub>	R <sub>1</sub>	R <sub>2</sub>	Measured Output Value
t <sub>PD</sub> , t <sub>CO</sub>	Closed	Closed	30 pF	1.6K Ω	1.6K Ω	V <sub>CC</sub> /2
t <sub>EA</sub>	Z → H: Open Z → L: Closed	Z → H: Closed Z → L: Open				V <sub>CC</sub> /2
t <sub>ER</sub>	H → Z: Closed L → Z: Closed	H → Z: Closed L → Z: Open	5 pF			H → Z: V <sub>OH</sub> - 0.5 V L → Z: V <sub>OL</sub> + 0.5 V

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## TYPICAL $I_{CC}$ CHARACTERISTICS

$V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$



**$I_{CC}$  vs. Frequency**

18956D-015

The selected "typical" pattern utilized 50% of the device resources. Half of the macrocells were programmed as registered, and the other half were programmed as combinatorial. Half of the available product terms were used for each macrocell. On any vector, half of the outputs were switching.

By utilizing 50% of the device, a midpoint is defined for  $I_{CC}$ . From this midpoint, a designer may scale the  $I_{CC}$  graphs up or down to estimate the  $I_{CC}$  requirements for a particular design.



## ENDURANCE CHARACTERISTICS

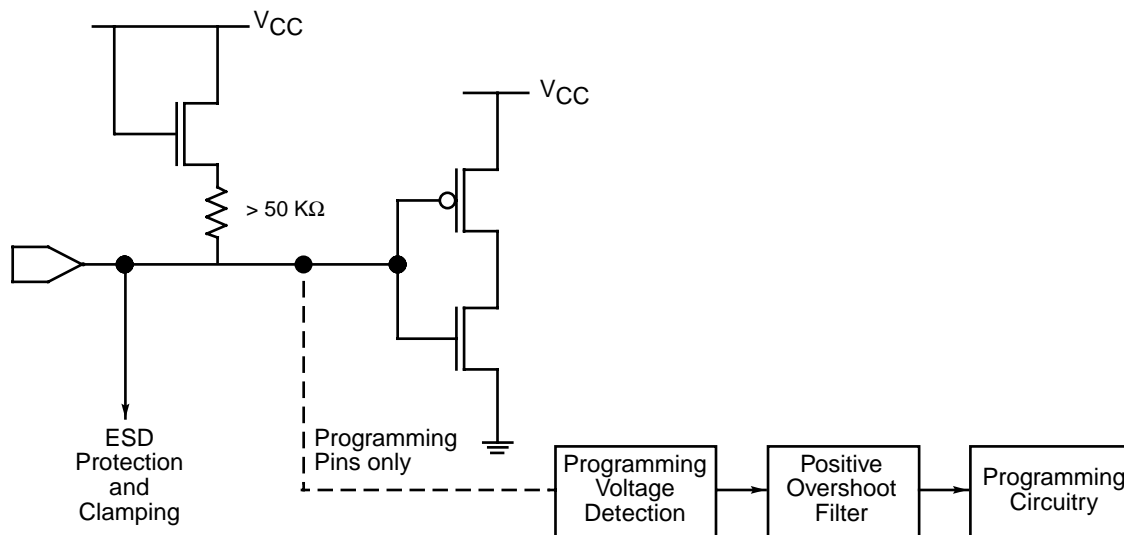
The PALLV22V10 is manufactured using Vantis' advanced electrically-erasable (EE) CMOS process. This technology uses an EE cell to replace the fuse link used in bipolar parts. As a result, the device can be erased and reprogrammed—a feature which allows 100% testing at the factory.

Symbol	Parameter	Test Conditions	Value	Unit
$t_{DR}$	Min Pattern Data Retention Time	Max Storage Temperature	10	Years
		Max Operating Temperature	20	Years
N	Min Reprogramming Cycles	Normal Programming Conditions	100	Cycles

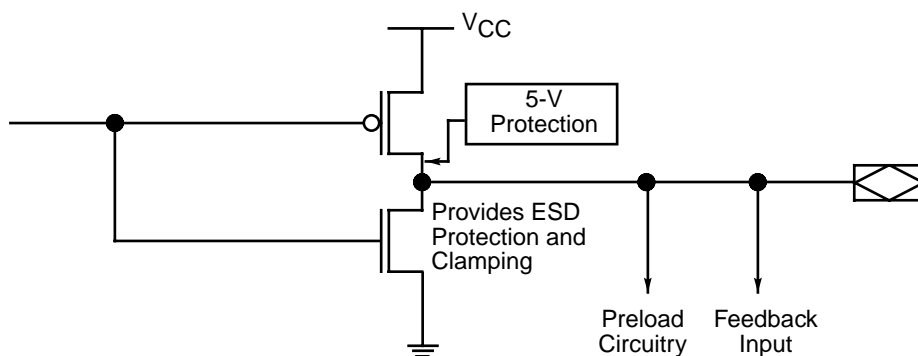
## ROBUSTNESS FEATURES

The PALLV22V10 has some unique features that make it extremely robust, especially when operating in high speed design environments. Input clamping circuitry limits negative overshoot, eliminating the possibility of false clocking caused by subsequent ringing. A special noise filter makes the programming circuitry completely insensitive to any positive overshoot that has a pulse width of less than about 100 ns.

## INPUT/OUTPUT EQUIVALENT SCHEMATICS



Typical Input



Typical Output

18956D-017

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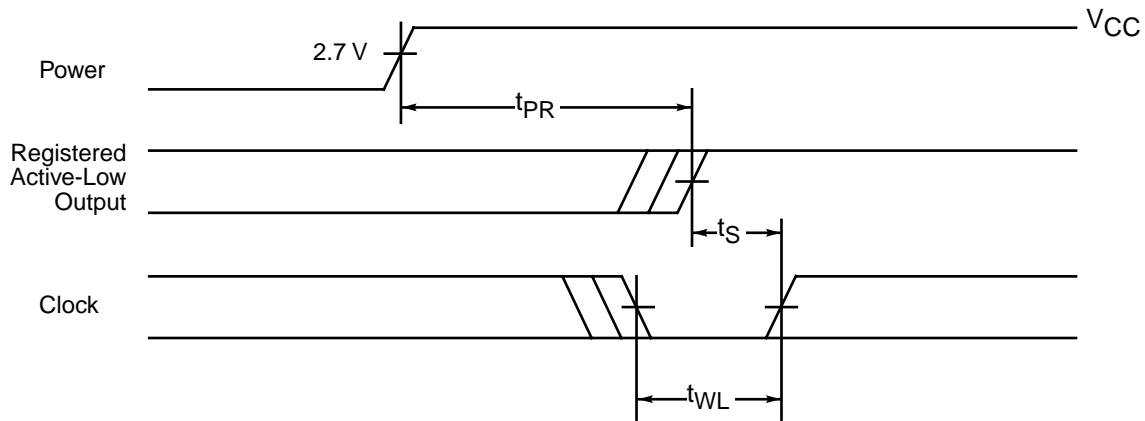


## POWER-UP RESET

The power-up reset feature ensures that all flip-flops will be reset to LOW after the device has been powered up. The output state will depend on the programmed pattern. This feature is valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and the wide range of ways  $V_{CC}$  can rise to its steady state, two conditions are required to ensure a valid power-up reset. These conditions are:

- ◆ The  $V_{CC}$  rise must be monotonic.
- ◆ Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Description	Max	Unit
$t_{PR}$	Power-Up Reset Time	1000	ns
$t_S$	Input or Feedback Setup Time	See Switching Characteristics	
$t_{WL}$	Clock Width LOW		



18956D-018

Figure 3. Power-Up Reset Waveform





## TYPICAL THERMAL CHARACTERISTICS

### PALLV22V10-10

Measured at 25°C ambient. These parameters are not tested.

Parameter Symbol	Parameter Description	Typ		Unit	
		SKINNY DIP	PLCC		
$\theta_{jc}$	Thermal impedance, junction to case	26	20	°C/W	
$\theta_{ja}$	Thermal impedance, junction to ambient	86	69	°C/W	
$\theta_{jma}$	Thermal impedance, junction to ambient with air flow	200 lfm air	72	57	°C/W
		400 lfm air	65	52	°C/W
		600 lfm air	60	47	°C/W
		800 lfm air	55	45	°C/W

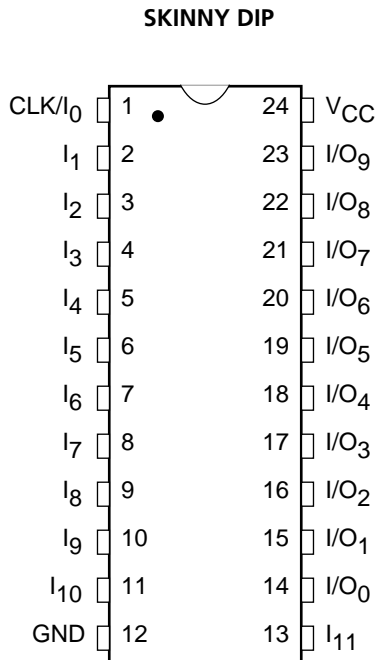
#### Plastic $\theta_{jc}$ Considerations

The data listed for plastic  $\theta_{jc}$  are for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the  $\theta_{jc}$  measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore,  $\theta_{jc}$  tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.

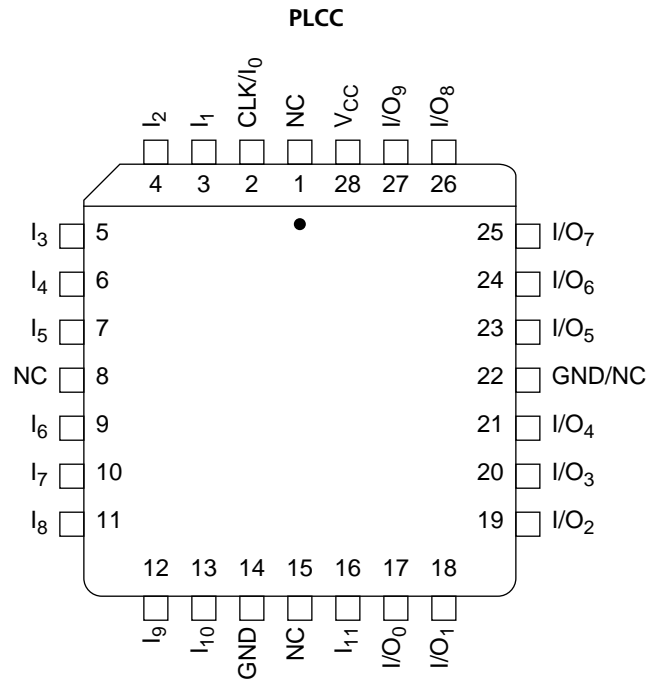


## CONNECTION DIAGRAMS

### Top View



18956D-002



18956D-003

**Note:**

Pin 1 is marked for orientation.

### PIN DESIGNATIONS

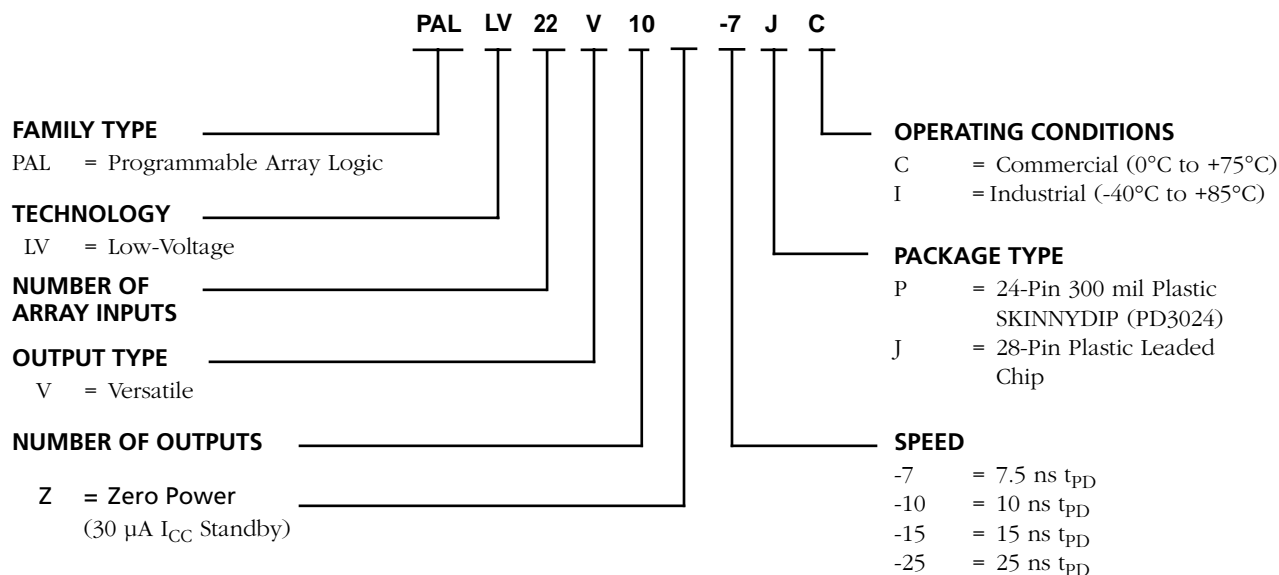
- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V<sub>CC</sub> = Supply Voltage



## ORDERING INFORMATION

### Commercial and Industrial Products

Vantis programmable logic products for commercial and industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of these elements:



Valid Combinations	
PALLV22V10-7	JC
PALLV22V10-10	PC, JC
PALLV22V10-15	PC, JC, JI
PALLV22V10Z-25	PI, JI

#### Valid Combinations

The Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Vantis sales office to confirm availability of specific valid combinations and to check on newly released combinations.

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